

Appl. No. 10/707,718
Amdt. dated April 27, 2006
Reply to Office action of February 08, 2006

AMENDMENTS TO THE CLAIMS

1. (Original) A computer system comprising:
a housing;
5 a motherboard installed inside the housing, the motherboard comprising:
a top surface;
a bottom surface; and
a central processing unit installed on the bottom surface for processing data;
a cage installed on a region inside of the housing and adjacent to the top surface of
10 the motherboard; and
at least an integrated drive electronics device installed inside the cage.
2. (Original) The computer system of claim 1 further comprising a first heat-ventilating
device installed on a region inside of the housing and adjacent to the bottom surface
15 of the motherboard for ventilating heat generated by the central processing unit to a
region outside of the housing.
3. (Original) The computer system of claim 1, wherein the first heat-ventilating device
is a pipeline cooler.
20
4. (Original) The computer system of claim 2 further comprising at least a first
heat-ventilating hole installed on the housing and adjacent to the bottom surface of
the motherboard, the first heat-ventilating device ventilating heat generated by the
central processing unit through the first heat-ventilating hole and to a region outside
25 of the housing.
5. (Original) The computer system of claim 1 further comprising a second
heat-ventilating device installed on a region inside of the housing and adjacent to the

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top surface of the motherboard for ventilating heat generated by the integrated drive electronics device to a region outside of the housing.

- 5 6. (Original) The computer system of claim 5, wherein the second heat-ventilating device is a fan cooler.
- 10 7. (Original) The computer system of claim 5 further comprising at least a second heat-ventilating hole installed on the housing and adjacent to the top surface of the motherboard, the second heat-ventilating device ventilating heat generated by the integrated drive electronics device through the second heat-ventilating hole and to a region outside of the housing.
- 15 8. (Original) The computer system of claim 1 further comprising at least a memory slot.
9. (Currently Amended) The computer system of claim 8, wherein the memory slot is obliquely installed on the bottom surface of the motherboard obliquely with respect to the bottom surface of the motherboard.
- 20 10. (Original) The computer system of claim 9, wherein the obliquely installed memory slot has a height smaller than that of the central processing unit.
11. (Original) The computer system of claim 1 further comprising a motherboard cage installed on top of the top surface of the motherboard and beneath the cage.
- 25 12. (Original) The computer system of claim 11, wherein the motherboard cage comprises at least a positioning aperture and the cage comprises at least a positioning device corresponding to the positioning aperture for plugging into the positioning aperture when the cage is mounted on the motherboard cage.

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13. (Currently Amended) The computer system of claim 11, wherein the motherboard cage comprises a plurality of ~~connectors~~ headers.
- 5 14. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a hard disk drive.
15. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a card reader.
- 10 16. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a CD-ROM drive.
17. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a floppy disk drive.
- 15 18. (Original) The computer system of claim 1, wherein the cage comprises a plurality of connectors.